503637693 01/06/2016

EPAS ID: PAT3684326

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE: NEW ASSIGNMENT

NATURE OF CONVEYANCE: ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
CHE-CHENG CHANG	12/24/2015
CHIH-HAN LIN	12/24/2015
HORNG-HUEI TSENG	12/28/2015

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	NO.8, LI-HSIN RD.6
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14987598

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Correspondent Name: BURNS ISRAELSEN
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ATTORNEY DOCKET NUMBER: T1516.10271US02

NAME OF SUBMITTER: R. BURNS ISRAELSEN

SIGNATURE: /R. Burns Israelsen, Reg.No. 42685/

DATE SIGNED: 01/06/2016

Total Attachments: 2

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PATENT 503637693 REEL: 037424 FRAME: 0653

ASSIGNMENT

This assignment agreement is applicable to an invention entitled (Invention Title)				
Semiconductor Structure and Manufacturing Method Thereof				
The PATENT RIGHTS referred to in this agreement are:				
(check one) \(\sum \) a patent application for this invention, executed by the ASSIGNOR(S)				
concurrently with this assignment.				
U.S. patent application Serial No,filed				
☐a U.S. patent application based on PCT International Application				
Nofiled on (date)(U.S. patent application				
Serial No, if known).				
U.S. patent No, issued				
The PATENT RIGHTS also include all divisions, reissues, continuations and extensions of				
the patents and patent applications identified above.				
The PATENT RIGHTS assigned under this agreement are:				
(check one) ⊠U.S. patent rights only.				
Worldwide patent rights. In this case, the assignee shall have the right to				
claim the benefit of the filing date of any U.S. or foreign patent application				
for this invention.				
The ASSIGNOR(S) referred to in this agreement is (or are) the inventor(s) whose signatures				
appear on page 2 of this Assignment and any Supplemental Sheet(s).				
The ASSIGNEE referred to in this agreement is:				
(Name of Assignee) TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.				
(Address) NO.8, LI-HSIN RD.6, SCIENCE-BASED INDUSTRIAL PARK, HSINCHU,				
<u>TAIWAN 300, R.O.C.</u>				
The ASSIGNEE is:				
(check one) ☐ An individual.				
☐A Partnership.				
☑A Corporation of <u>TAIWAN, R.O.C.</u> (specify state or country)				
(other)				

The ASSIGNOR(S), in consideration of \$10.00 paid by the ASSIGNEE, and other good and valuable consideration, receipt of which is acknowledged, hereby assign(s) the following rights to the ASSIGNEE, its successors and assigns:

the full and exclusive right to the invention;

the entire right, title and interest in and to the PATENT RIGHTS;

the right to sue and recover for any past infringement; and

the right to claim priority under 35 USC 119, 35 USC 120, or any other applicable provisions, based on any earlier patent applications for this invention.

PATENT REEL: 037424 FRAME: 0654 THIS IS PAGE 2 OF AN ASSIGNMENT FROM THE INVENTOR(S) TO ASSIGNEE: TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD. INVENTION TITLE: Semiconductor Structure and Manufacturing Method Thereof

As to all U.S. patent applications assigned under this agreement, the ASSIGNOR(S) hereby authorize(s) and request(s) the Commissioner of Patents and Trademark to issue all Letters Patent to the ASSIGNEE as the assignee of the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE, its successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE, or its representatives, any fact known to the ASSIGNOR(S) with respect to said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause and all Letter Patent to be issued to said ASSIGNEE, make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention.

The ASSIGNOR(S) authorize(s) the attorneys and agents who have the power of attorney in this application to check any appropriate boxes and to insert the Serial Number and filing date in this document after it has been executed.

Che-Cheng CHANG	Cho-Chang Chaig	2015/12/24
Name of sole or first inventor	Signature	Date
Chih-Han LIN	itih - Hantin	2015/12/24
Name of second inventor, if any	Signature	Date
Horng-Huei TSENG	Hozna-Hila: Trans	1 Dec. 28 2015
Name of third inventor, if any	Signature	Date

PATENT REEL: 037424 FRAME: 0655

RECORDED: 01/06/2016